

SID

Factory: Rot am See

Article:

ML6

Provided:

Customer:

Date:

03.04.2026

WÜRTH  
ELEKTRONIK  
MORE THAN  
YOU EXPECT

Processtechnology: B: undefined

Material Text	Mat. Nr.	µm	Stackup	Process overview
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A-RS Kupferfolie-018my 330x490mm	50200238	18	VS	1	B00
C-RAS-FR4-PP-2116-H53-TG150-HF-EM-37B...	50203001	192		2	
C-RAS-FR4-PP-1080-H63-TG150-HF-EM-37B...	50203000	0		3	
		18	L2	4	
C-RS-FR4-ML-0.406mm-018+018-TG150-HF-...	50203030	407			
		18	L3		
C-RAS-FR4-PP-1080-H63-TG150-HF-EM-37B...	50203000	216		5	
C-RAS-FR4-PP-1080-H63-TG150-HF-EM-37B...	50203000	0		6	
C-RAS-FR4-PP-1080-H63-TG150-HF-EM-37B...	50203000	0		7	
		18	L4	8	
C-RS-FR4-ML-0.406mm-018+018-TG150-HF-...	50203030	407			
		18	L5		
C-RAS-FR4-PP-1080-H63-TG150-HF-EM-37B...	50203000	192		9	
C-RAS-FR4-PP-2116-H53-TG150-HF-EM-37B...	50203001	0		10	
A-RS Kupferfolie-018my 330x490mm	50200238	18	RS	11	

Thickness after Pressing

B00:

1440 µm

Tol+:

155 µm

Tol-:

155 µm

Dmax:

1595 µm

Dmin:

1285 µm

Thickness over all

0 µm

Tol+:

0 µm

Tol-:

0 µm

Dmax:

0 µm

Dmin:

0 µm

Demand for customer

Thickness (D):

1550 µm

Tol+:

155 µm

Tol-:

155 µm

Dmax:

1705 µm

Dmin:

1395 µm

Measuring point: (05) over SM and galv. Cu; both sides

nominal:

1522 µm

Version 1.2.20.35

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